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WPI Acc no: 2003-003044/

XRAM Acc no: C2003-001119

XRPX Acc No: N2003-002301

Thermally conductive sheet for transistor, comprises thermally conductive tabular particle dispersed in binder resin, which is oriented vertically in thickness direction and contains particles with varying grain size

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Patent Family (1 patents, 1 countries)

Patent Number	Kind	Date	Application Number	Kind	Date	Update	Type
JP 2002164481	A	20020607	JP 2000345734	A	20001113	200301	B

Priority Applications (no., kind, date): JP 2000345734 A 20001113

Patent Details

Patent Number	Kind	Lan	Pgs	Draw	Filing Notes
JP 2002164481	A	JA	5	1	

Alerting Abstract JP A

NOVELTY - A thermally conductive sheet (1) contains a binder resin (2) and thermally conductive particle dispersed in the binder resin. The thermally conductive particle is a tabular particle which is oriented vertically along thickness direction. The thermally conductive particle contains 2 or more types of particles differing in grain size.

USE - For making pyrogenic electronic components such as transistor, and electronic device such as personal computer.

ADVANTAGE - Thermally conductive sheet having high heat conductivity is provided, without mixing many particles and without impairing softness.

DESCRIPTION OF DRAWINGS - The figure shows the fragmentary sectional view of the thermally conductive sheet. (Drawing includes non-English language text).

1 Thermally conductive sheet

2 Binder resin

3 Thermally conductive particle with large grain size

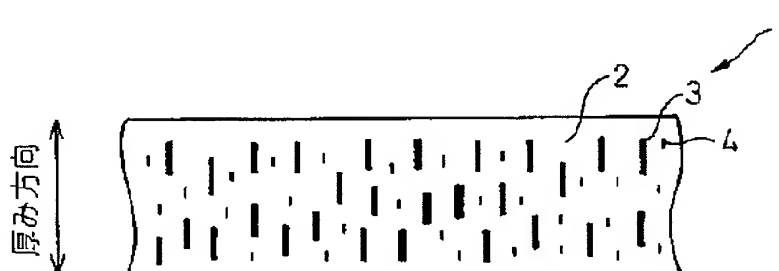
4 Thermally conductive particle with small grain size

Technology Focus

INORGANIC CHEMISTRY - Preferred Particles: The thermally conductive particle contains large thermally conductive particles (3) with grain size of 30-100 μm , and small thermally conductive particles with grain size of 0.5-20 μm . The particles with large grain size and small grain size are mixed in the volume ratio of 9:1-1:9.

Main Drawing Sheet(s) or Clipped Structure(s)

図 1



Title Terms /Index Terms/Additional Words: THERMAL; CONDUCTING; SHEET; TRANSISTOR; COMPRISE; TABULAR; PARTICLE; DISPERSE; BIND; RESIN; ORIENT; VERTICAL; THICK; DIRECTION; CONTAIN; VARY; GRAIN; SIZE

Class Codes

International Patent Classification

IPC	Class Level	Scope	Position	Status	Version Date
H01L-023/36			Main		"Version 7"
C08J-005/18; C08K-007/00; C08L-101/00; C09K-005/08			Secondary		"Version 7"

Original Publication Data by Authority

Japan

Publication No. **JP 2002164481 A (Update 200301 B)**

Publication Date: 20020607

HEAT CONDUCTIVE SHEET

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Language: JA (5 pages, 1 drawings)

Application: JP 2000345734 A 20001113 (Local application)

Original IPC: H01L-23/36(A) C08J-5/18(B) C08K-7/00(B) C08L-101/00(B) C09K-5/08(B)

Current IPC: H01L-23/36(A) C08J-5/18(B) C08K-7/00(B) C08L-101/00(B) C09K-5/08(B)